

FOR IMMEDIATE RELEASE

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PRESS RELEASE

MacDermid Alpha presents, at IMAPS Device Packaging Conference 2023, on powering the future of advanced semiconductor solutions for packaging designs and overcoming the challenges of miniaturization to enable greater device reliability.

(Waterbury, CT USA) - March 6, 2023 – MacDermid Alpha, one of the world's largest providers of solutions for circuitry, assembly, and semiconductor manufacturers within the electronics industry will present its latest research on high-speed copper plating at the 19th Annual Device Packaging Conference (DPC 2023), held March 13-16, at the We-Ko-Pa Conference Center in Fountain Hills, Arizona. Engage the industry experts at booth 31-32, where MacDermid Alpha will showcase the performance benefits of advanced materials for die attach, chip fabrication, and wafer-level packaging.

Sean Fleuriel, Research Chemist, will present a paper at the technical conference, titled "High-Speed Copper Plating Process for IC Substrate". In this paper, Sean presents findings from an acid copper electrolyte utilized for plating 2-in-1 redistribution layers (RDL), with small vias and fine lines down to 10µm wide. The electrolytic process successfully plated these features, while maintaining a uniform surface across the panel that met the demanding physical requirements for IC substrate applications. Sean will explore the new high-speed findings in greater detail, revealing new degrees of control unavailable in VCPs, and cover the benefits of the high-speed tool to reduce plating time.

MacDermid Alpha is powering the future of advanced semiconductor solutions that exceed demanding packaging design requirements and help overcome the challenges of miniaturization thereby enabling greater device reliability. Highlighted at the show will be:

- Systek®, MacDermid Alpha's family of high-performance build-up processes for IC Substrates and their integrated leadframe package portfolio which spans the entire process of building QFN packages from leadframe roughening and improving sidewall solderability for enhanced reliability to selective EMC plating for higher functionality.

- NOVAFAB® NANOTWIN Cu is a ready-to-use, high-purity copper electroplating process designed for use with soluble or insoluble anodes. This system enables low-temperature, high-reliability copper-to-copper interconnects for die-to-die (D2D), die-to-wafer (D2W), and wafer-to-wafer (W2W) bonding.

Additionally, for solutions designed for the challenges of power electronics, MacDermid Alpha will share information on the latest capabilities of the ALPHA® ARGOMAX® portfolio of sinter materials and ATROX® conductive and non-conductive die attach pastes and films will be available. ALPHA® ARGOMAX® engineered sinter materials are proven to have the best process times and reliability while providing flexible and easy-to-use form factors that reduce the capital cost and time to market. ATROX® conductive die attach products are an enabler for package shrinkage and higher power density packaging, designed for excellent workability and processing, and offer proven performance across a range of exposed pad power packages.

Let's start a conversation at booth 31-32; the team from MacDermid Alpha will be ready to discuss how to elevate your process with an integrated 'start to finish' roadmap featuring some of the most advanced technologies on the market, backed by extensive R&D facilities, a robust supply chain, and extraordinary customer service. Established brands aligned under MacDermid Alpha Electronics Solutions include Alpha®, Compugraphics, Electrolube®, Kester®, and MacDermid Enthone®. MacDermid Alpha will resolve your pain points today, tomorrow, and beyond. Discover how we make a difference by visiting www.macdermidalpha.com

About MacDermid Alpha

MacDermid Alpha enables electronics interconnection through the innovative specialty chemicals and materials from our Alpha®, Compugraphics, Electrolube®, Kester®, and MacDermid Enthone® brands. We serve all global regions and all steps of device manufacturing within every segment of the electronics supply chain. The experts in our Semiconductor Solutions, Circuitry Solutions, and Assembly Solutions divisions collaborate with OEMs and fabricators in the implementation of new technologies that redefine what is possible in device design. Our world class technical service is constantly at hand to ensure optimized outcomes in yield and productivity. Our solutions can increase throughput, reduce carbon footprints, lower the total cost of ownership, and enable electronics innovation.

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